RV1S9160A

HIGH CMR, 15Mbps CMOS OUTPUT, LOW FORWARD-CURRENT(I_F) 3.3V/5V OPERATION, 5-PIN SOP PHOTOCOUPLER

DESCRIPTION

The RV1S9160A is a photocoupler featuring high-speed switching up to 15Mbps with active low output logic which consist of an AlGaAs LED on the input side and an integrated circuit with a photodiode on the output.

This product enables to low current operation on 3.3V/5V power supply with high noise-tolerant CMR:50kV/μs min. and high temperature operation up to T_A = 125°C in logic interface circuit.

FEATURES

- High speed communication (15 Mbps)
- High temperature operation (-40 to +125°C)
- High common mode (dv/dt) tolerant (CM_H, CM_L = ±50 kV/μs MIN.)
- High isolation voltage (BV = 3750 Vr.m.s.)
- Low input drive current (I_FH,L = 2.0 mA MAX.)
- Low voltage power supply operation (V_DD = 2.7 V ~ 5.5 V)
- Low pulse width distortion (PWD = 20 ns MAX.)
- Ordering number of tape product: RV1S9160ACCSP-100x#KC0 : 2500 pcs/reel
- Pb free product
- Safety standards approval
  - UL : UL1577, Double protection
  - CSA : CAN/CSA-C22.2 No.62368-1, Basic insulation
  - VDE : DIN EN 60747-5-5 (Option)

APPLICATIONS

- Industrial inverter
- AC Servo
- FA Network
- Measurement, Control Equipment

TRUTH TABLE

<table>
<thead>
<tr>
<th>LED</th>
<th>OUTPUT</th>
</tr>
</thead>
<tbody>
<tr>
<td>ON</td>
<td>L</td>
</tr>
<tr>
<td>OFF</td>
<td>H</td>
</tr>
</tbody>
</table>

Start of mass production
Jun.2019
PACKAGE DIMENSIONS (UNIT : mm)

Weight: 0.08g (typ.)

PHOTOCOUPLER CONSTRUCTION

<table>
<thead>
<tr>
<th>Parameter</th>
<th>MIN.</th>
</tr>
</thead>
<tbody>
<tr>
<td>Air Distance</td>
<td>4.2 mm</td>
</tr>
<tr>
<td>Creepage Distance</td>
<td>4.2 mm</td>
</tr>
<tr>
<td>Isolation Distance</td>
<td>0.2 mm</td>
</tr>
</tbody>
</table>
MARKING EXAMPLE

![Marking Example Diagram]

*Applicable type numbers are listed below.

*) RV1S9160ACCSP-100x

Marking type number. "RV1S" and "ACCSP-100x" are omitted from original type number.

ORDERING INFORMATION

<table>
<thead>
<tr>
<th>Part Number</th>
<th>Order Number</th>
<th>Solder Plating Specification</th>
<th>Packing Style</th>
<th>Safety Standard Approval</th>
<th>Application Part Number</th>
</tr>
</thead>
<tbody>
<tr>
<td>RV1S9160ACCSP-100C</td>
<td>RV1S9160ACCSP-100C#SC0</td>
<td>Pb-Free (Ni/Pd/Au)</td>
<td>20 pcs (Tape 20 pcs cut)</td>
<td>Standard products (UL, CSA approved)</td>
<td>RV1S9160A</td>
</tr>
<tr>
<td>RV1S9160ACCSP-100C</td>
<td>RV1S9160ACCSP-100C#KC0</td>
<td>Embossed Tape 2 500 pcs/reel</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>RV1S9160ACCSP-100V</td>
<td>RV1S9160ACCSP-100V#SC0</td>
<td>20 pcs (Tape 20 pcs cut)</td>
<td>UL, CSA, DIN EN 60747-5-5 approved</td>
<td></td>
<td></td>
</tr>
<tr>
<td>RV1S9160ACCSP-100V</td>
<td>RV1S9160ACCSP-100V#KC0</td>
<td>Embossed Tape 2 500 pcs/reel</td>
<td></td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

Notes: *1. For the application of the Safety Standard, following part number should be used.

ABSOLUTELY MAXIMUM RATINGS (T_A = 25°C, unless otherwise specified)

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Symbol</th>
<th>Ratings</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>Diode</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Forward Current</td>
<td>I_F</td>
<td>20</td>
<td>mA</td>
</tr>
<tr>
<td>Reverse Voltage</td>
<td>V_R</td>
<td>5</td>
<td>V</td>
</tr>
<tr>
<td>Detector</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Supply Voltage</td>
<td>V_DD</td>
<td>6</td>
<td>V</td>
</tr>
<tr>
<td>Output Voltage</td>
<td>V_O</td>
<td>6</td>
<td>V</td>
</tr>
<tr>
<td>Output Current</td>
<td>I_O</td>
<td>10</td>
<td>mA</td>
</tr>
<tr>
<td>Power Dissipation</td>
<td>P_c</td>
<td>200</td>
<td>mW</td>
</tr>
<tr>
<td>Isolation Voltage</td>
<td>B_V</td>
<td>3750</td>
<td>V_r.m.s.</td>
</tr>
<tr>
<td>Operating Ambient Temperature</td>
<td>T_A</td>
<td>-40 to +125</td>
<td>°C</td>
</tr>
<tr>
<td>Storage Temperature</td>
<td>T_stg</td>
<td>-55 to +150</td>
<td>°C</td>
</tr>
</tbody>
</table>

Notes: 1. Reduced to 0.93 mA/°C at T_A = 110°C or more
2. Reduced to 4.57 mW/°C at T_A = 90°C or more
3. AC Voltage for 1 minute at T_A = 25°C, RH = 60% between input and output.
4. Pins 1-2 shorted together, 3-5 shorted together.
RECOMMENDED OPERATING CONDITIONS

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Symbol</th>
<th>MIN.</th>
<th>TYP.</th>
<th>MAX.</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>Low Level forward voltage</td>
<td>VFL</td>
<td>0</td>
<td>0.8</td>
<td></td>
<td>V</td>
</tr>
<tr>
<td>High Level Forward Current</td>
<td>IFH</td>
<td>3</td>
<td>6</td>
<td></td>
<td>mA</td>
</tr>
<tr>
<td>Supply Voltage</td>
<td>VDD</td>
<td>2.7</td>
<td>5.5</td>
<td></td>
<td>V</td>
</tr>
</tbody>
</table>

ELECTRICAL CHARACTERISTICS
(TA = -40 to +125°C, VDD = 2.7 to 5.5 V, unless otherwise specified)

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Symbol</th>
<th>Conditions</th>
<th>MIN.</th>
<th>TYP.*</th>
<th>MAX.</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>Diode Forward Voltage</td>
<td>Vf</td>
<td>IF = 6 mA, TA = 25°C</td>
<td>1.4</td>
<td>1.55</td>
<td>1.7</td>
<td>V</td>
</tr>
<tr>
<td>Diode Reverse Current</td>
<td>IR</td>
<td>VR = 3 V, TA = 25°C</td>
<td></td>
<td>10</td>
<td></td>
<td>μA</td>
</tr>
<tr>
<td>Diode Terminal Capacitance</td>
<td>CT</td>
<td>VF = 0 V, f = 1 MHz, TA = 25°C</td>
<td>30</td>
<td></td>
<td></td>
<td>pF</td>
</tr>
<tr>
<td>Detector High Level Output Current</td>
<td>IDOH</td>
<td>IF = 0 mA</td>
<td>1.1</td>
<td>2</td>
<td></td>
<td>mA</td>
</tr>
<tr>
<td>Detector Low Level Output Current</td>
<td>IDOL</td>
<td>IF = 3 mA</td>
<td>1.0</td>
<td>2</td>
<td></td>
<td>mA</td>
</tr>
<tr>
<td>Detector High Level Output Voltage</td>
<td>VOH</td>
<td>IO = -3.2 mA, IF = 0 mA</td>
<td>VDD-1.0</td>
<td>VDD</td>
<td></td>
<td>V</td>
</tr>
<tr>
<td>Detector Low Level Output Voltage</td>
<td>VOL</td>
<td>IO = 3.2 mA, IF = 3 mA</td>
<td>0.13</td>
<td>0.4</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Coupled Threshold Input Voltage (H to L)</td>
<td>IFHL</td>
<td>VDH &lt; 0.4 V</td>
<td>1.0</td>
<td>2.0</td>
<td></td>
<td>mA</td>
</tr>
<tr>
<td>Coupled Isolation Resistance</td>
<td>R-O</td>
<td>VO = 1 kVDC, RH = 40 to 60%, TA = 25°C</td>
<td>1011</td>
<td></td>
<td></td>
<td>Ω</td>
</tr>
<tr>
<td>Coupled Isolation Capacitance</td>
<td>CI-O</td>
<td>V = 0 V, f = 1 MHz, TA = 25°C</td>
<td>0.5</td>
<td></td>
<td></td>
<td>pF</td>
</tr>
<tr>
<td>Propagation Delay Time (H to L)</td>
<td>tPHL</td>
<td>IF = 3 mA ⇔ 0 mA</td>
<td>VDD = 3.3 V, 5 V</td>
<td>40</td>
<td>60</td>
<td>ns</td>
</tr>
<tr>
<td>Propagation Delay Time (L to H)</td>
<td>tPLH</td>
<td>IC = 15 pF</td>
<td></td>
<td>38</td>
<td>60</td>
<td></td>
</tr>
<tr>
<td>Pulse Width Distortion*2</td>
<td>PWD</td>
<td></td>
<td>2</td>
<td>20</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Propagation Delay Skew</td>
<td>tPSK</td>
<td></td>
<td></td>
<td>25</td>
<td></td>
<td></td>
</tr>
<tr>
<td>Rise Time</td>
<td>tr</td>
<td></td>
<td>5</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Fall Time</td>
<td>tf</td>
<td></td>
<td>5</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Common Mode Transient Immunity at High Level Output*3</td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Common Mode Transient Immunity at Low Level Output*3</td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
</tbody>
</table>

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Mar 06, 2020
Note2: 1. Typical values at $T_A = 25^\circ C$
2. Test circuit for propagation delay time measurement

![Test circuit for propagation delay time measurement diagram](image1)

Remark $C_L$ includes probe and stray wiring capacitance.

3. Test circuit for common mode transient immunity measurement

![Test circuit for common mode transient immunity measurement diagram](image2)

Remark $C_L$ includes probe and stray wiring capacitance.

**USAGE CAUTIONS**

1. This product is weak for static electricity by designed with high-speed integrated circuit so protect against static electricity when handling.
2. By-pass capacitor of more than 0.1 $\mu$F is used between $V_{DD}$ and GND near device. Also, ensure that the distance between the leads of the photocoupler and capacitor is no more than 10 mm.
3. Avoid storage at a high temperature and high humidity.
TYPICAL CHARACTERISTICS (\(T_A = 25^\circ C\), unless otherwise specified)

Remark The graphs indicate nominal characteristics.
Remark The graphs indicate nominal characteristics.
TAPING SPECIFICATIONS (UNIT : mm)

Taping Direction

Outline and Dimensions (Tape)

Outline and Dimensions (Reel)

Packing: 2 500 pcs/reel
RECOMMENDED MOUNT PAD DIMENSIONS (UNIT : mm)

Remark All dimensions in this figure must be evaluated before use.
NOTES ON HANDLING

1. Recommended soldering conditions
   (1) Infrared reflow soldering
      • Peak reflow temperature  260°C or below (package surface temperature)
      • Time of peak reflow temperature  10 seconds or less
      • Time of temperature higher than 220°C  60 seconds or less
      • Time to preheat temperature from 120 to 180°C  120±30 s
      • Number of refloows  Three
      • Flux  Rosin flux containing small amount of chlorine
        (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

   Recommended Temperature Profile of Infrared Reflow

   (2) Wave soldering
      • Temperature  260°C or below (molten solder temperature)
      • Time  10 seconds or less
      • Preheating conditions  120°C or below (package surface temperature)
      • Number of times  One (Allowed to be dipped in solder including plastic mold portion.)
      • Flux  Rosin flux containing small amount of chlorine (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

   (3) Soldering by Soldering Iron
      • Peak Temperature (lead part temperature)  350°C or below
      • Time (each pins)  3 seconds or less
      • Flux  Rosin flux containing small amount of chlorine
        (The flux with a maximum chlorine content of 0.2 Wt% is recommended.)

   (a) Soldering of leads should be made at the point 1.5 to 2.0 mm from the root of the lead
   (b) Please be sure that the temperature of the package would not be heated over 100°C

   (4) Cautions
      • Flux Cleaning
        Avoid cleaning with Freon based or halogen-based (chlorinated etc.) solvents.
      • Do not use adhesives or coating materials including halogens to fix this device.

2. Cautions regarding noise
   Be aware that when voltage is applied suddenly between the photocoupler’s input and output or between $V_{DD}$-GND at startup, the output transistor may enter the on state, even if the voltage is within the absolute maximum ratings.
### SPECIFICATION OF VDE MARKS LICENSE DOCUMENT

<table>
<thead>
<tr>
<th>Parameter</th>
<th>Symbol</th>
<th>Rating</th>
<th>Unit</th>
</tr>
</thead>
<tbody>
<tr>
<td>Climatic test class (IEC 60068-1/DIN EN 60068-1)</td>
<td></td>
<td>40/125/21</td>
<td></td>
</tr>
<tr>
<td>Dielectric strength</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>maximum operating isolation voltage</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Test voltage (partial discharge test, procedure a for type test and random test)</td>
<td>U_{IOHM}</td>
<td>710</td>
<td>V_{peak}</td>
</tr>
<tr>
<td>U_{pr} = 1.6 \times U_{IOHM}, P_d &lt; 5 pC</td>
<td>U_{IR}</td>
<td>1 136</td>
<td>V_{peak}</td>
</tr>
<tr>
<td>Test voltage (partial discharge test, procedure b for all devices)</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>U_{pr} = 1.875 \times U_{IOHM}, P_d &lt; 5 pC</td>
<td>U_{IR}</td>
<td>1 331</td>
<td>V_{peak}</td>
</tr>
<tr>
<td>Highest permissible overvoltage</td>
<td>U_{IOTM}</td>
<td>6 000</td>
<td>V_{peak}</td>
</tr>
<tr>
<td>Degree of pollution (IEC 60664-1/DIN EN 60664-1 (VDE 0110-1))</td>
<td></td>
<td>2</td>
<td></td>
</tr>
<tr>
<td>Comparative tracking index (IEC 60112/DIN EN 60112 (VDE 0303-11))</td>
<td>CTI</td>
<td>400</td>
<td></td>
</tr>
<tr>
<td>Material group (IEC 60664-1/DIN EN 60664-1 (VDE 0110-1))</td>
<td></td>
<td>II</td>
<td></td>
</tr>
<tr>
<td>Storage temperature range</td>
<td>T_{stg}</td>
<td>– 55 to +150</td>
<td>°C</td>
</tr>
<tr>
<td>Operating temperature range</td>
<td>T_{A}</td>
<td>–40 to +125</td>
<td>°C</td>
</tr>
<tr>
<td>Isolation resistance, minimum value</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>V_{O} = 500 V dc at T_{A} = 25°C</td>
<td>R_{is MIN.}</td>
<td>10^{12}</td>
<td>Ω</td>
</tr>
<tr>
<td>V_{O} = 500 V dc at T_{A} MAX. at least 100°C</td>
<td>R_{is MIN.}</td>
<td>10^{11}</td>
<td>Ω</td>
</tr>
<tr>
<td>Safety maximum ratings (maximum permissible in case of fault, see thermal derating curve)</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>Package temperature</td>
<td>T_{si}</td>
<td>150</td>
<td>°C</td>
</tr>
<tr>
<td>Current (input current Isi , Psi = 0)</td>
<td>Isi</td>
<td>200</td>
<td>mA</td>
</tr>
<tr>
<td>Power (output or total power dissipation)</td>
<td>Psi</td>
<td>300</td>
<td>mW</td>
</tr>
<tr>
<td>Isolation resistance</td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>V_{O} = 500 V dc at T_{A} = T_{si}</td>
<td>R_{is MIN.}</td>
<td>10^{9}</td>
<td>Ω</td>
</tr>
</tbody>
</table>

**Dependence of maximum safety ratings with package temperature**

![Dependence of maximum safety ratings with package temperature](image)
Method a) Destructive Test, Type and Sample Test

\[ U_{\text{IOTM}} = 6000V \]

\[ U_{pr} = 1136V \]

\[ U_{\text{IORM}} = 710V \]

\[ t_{1}, t_{2} = 1 \text{ to } 10 \text{ sec} \]

\[ t_{3}, t_{4} = 1 \text{ sec} \]

\[ t_{m}(\text{PARTIAL DISCHARGE}) = 10 \text{ sec} \]

\[ t_{\text{test}} = 12 \text{ sec} \]

\[ t_{\text{ini}} = 60 \text{ sec} \]

Method b) Non-destructive Test, 100% Production Test

\[ U_{pr} = 1331V \]

\[ U_{\text{IORM}} = 710V \]

\[ t_{3}, t_{4} = 0.1 \text{ sec} \]

\[ t_{m}(\text{PARTIAL DISCHARGE}) = 1.0 \text{ sec} \]

\[ t_{\text{test}} = 1.2 \text{ sec} \]
**Caution** GaAs Products

This product uses gallium arsenide (GaAs). GaAs vapor and powder are hazardous to human health if inhaled or ingested, so please observe the following points.

- Follow related laws and ordinances when disposing of the product. If there are no applicable laws and/or ordinances, dispose of the product as recommended below.

1. Commission a disposal company able to (with a license to) collect, transport and dispose of materials that contain arsenic and other such industrial waste materials.

2. Exclude the product from general industrial waste and household garbage, and ensure that the product is controlled (as industrial waste subject to special control) up until final disposal.

- Do not burn, destroy, cut, crush, or chemically dissolve the product.
- Do not lick the product or in any way allow it to enter the mouth.
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